

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

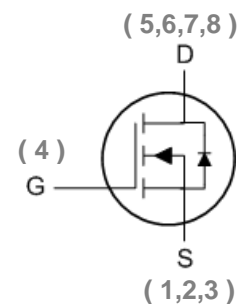
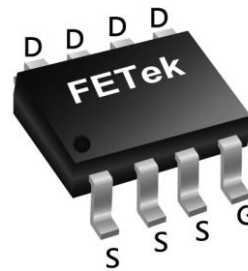
**Product Summary**


| BVDSS | RDSON | ID   |
|-------|-------|------|
| 100V  | 47mΩ  | 3.6A |

**Description**

The FKS0016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKS0016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**SOP8 Pin Configuration**

**Absolute Maximum Ratings**

| Symbol                   | Parameter                                  | Rating     | Units      |
|--------------------------|--|------------|------------|
| $V_{DS}$                 | Drain-Source Voltage                       | 100        | V          |
| $V_{GS}$                 | Gate-Source Voltage                        | $\pm 20$   | V          |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 3.6        | A          |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 2.9        | A          |
| $I_{DM}$                 | Pulsed Drain Current <sup>2</sup>          | 15         | A          |
| EAS                      | Single Pulse Avalanche Energy <sup>3</sup> | 36.5       | mJ         |
| $I_{AS}$                 | Avalanche Current                          | 27         | A          |
| $P_D @ T_A = 25^\circ C$ | Total Power Dissipation <sup>4</sup>       | 1.5        | W          |
| $T_{STG}$                | Storage Temperature Range                  | -55 to 150 | $^\circ C$ |
| $T_J$                    | Operating Junction Temperature Range       | -55 to 150 | $^\circ C$ |

**Thermal Data**

| Symbol          | Parameter  | Typ. | Max. | Unit         |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient <sup>1</sup> | ---  | 85   | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 24   | $^\circ C/W$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                       | Parameter                                      | Conditions  | Min. | Typ.  | Max.      | Unit                       |
|------------------------------|--|---|------|-------|-----------|----------------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$                           | 100  | ---   | ---       | V                          |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$  | ---  | 0.098 | ---       | $V/^\circ\text{C}$         |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V, I_D=3A$                                | ---  | ---   | 47        | m $\Omega$                 |
|                              |  | $V_{GS}=4.5V, I_D=2A$                               | ---  | ---   | 50        |                            |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=250\mu A$                       | 1.0  | ---   | 2.5       | V                          |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |   | ---  | -5.52 | ---       | $\text{mV}/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$       | ---  | ---   | 10        | $\mu A$                    |
|                              |  | $V_{DS}=80V, V_{GS}=0V, T_J=55^\circ\text{C}$       | ---  | ---   | 100       |                            |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V, V_{DS}=0V$                         | ---  | ---   | $\pm 100$ | nA                         |
| gfs                          | Forward Transconductance                       | $V_{DS}=5V, I_D=3A$                                 | ---  | 6.2   | ---       | S                          |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$               | ---  | 1.6   | ---       | $\Omega$                   |
| $Q_g$                        | Total Gate Charge (10V)                        | $V_{DS}=80V, V_{GS}=10V, I_D=3A$                    | ---  | 60    | ---       | nC                         |
| $Q_{gs}$                     | Gate-Source Charge                             |   | ---  | 9.2   | ---       |                            |
| $Q_{gd}$                     | Gate-Drain Charge                              |   | ---  | 9.9   | ---       |                            |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega$<br>$I_D=3A$ | ---  | 10.8  | ---       | ns                         |
| $T_r$                        | Rise Time                                      |   | ---  | 27    | ---       |                            |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |   | ---  | 56    | ---       |                            |
| $T_f$                        | Fall Time                                      |   | ---  | 24    | ---       |                            |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$              | ---  | 3848  | ---       | pF                         |
| $C_{oss}$                    | Output Capacitance                             |   | ---  | 137   | ---       |                            |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |   | ---  | 82    | ---       |                            |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                       | Min. | Typ. | Max. | Unit |
|----------|--|--|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                     | ---  | ---  | 3.6  | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,5</sup>     |  | ---  | ---  | 15   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$        | ---  | ---  | 1.2  | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=3A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$ | ---  | 25   | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |  | ---  | 29   | ---  | nC   |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=27A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

Typical Characteristics

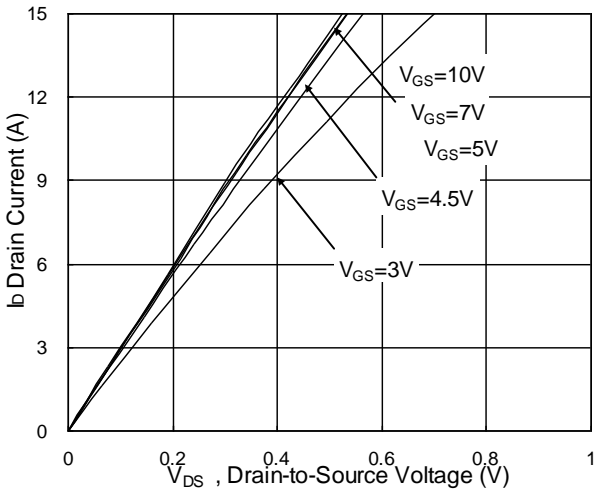


Fig.1 Typical Output Characteristics

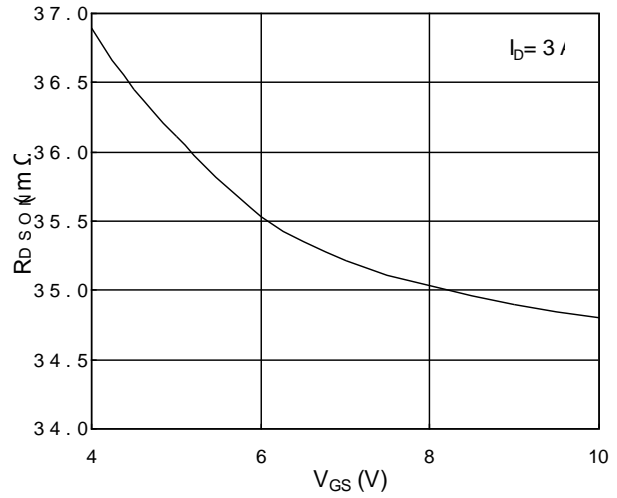


Fig.2 On-Resistance vs. Gate-Source

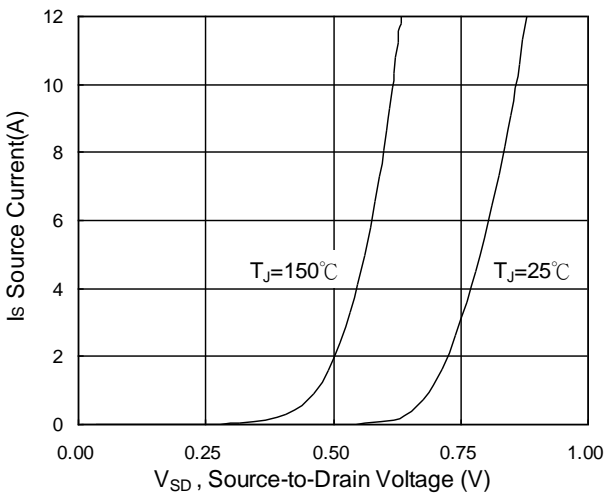


Fig.3 Forward Characteristics Of Reverse

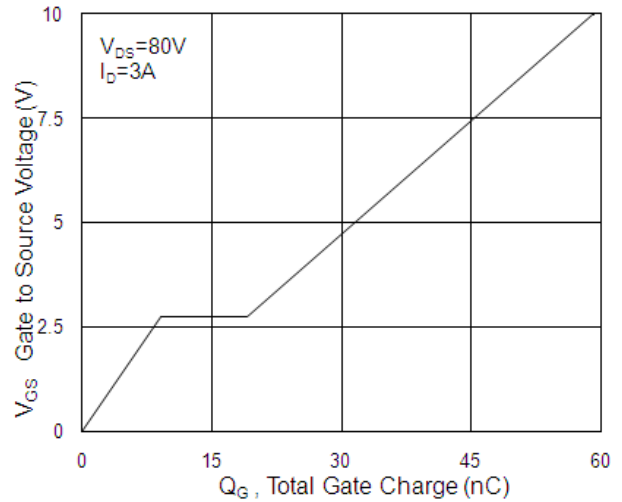


Fig.4 Gate-Charge Characteristics

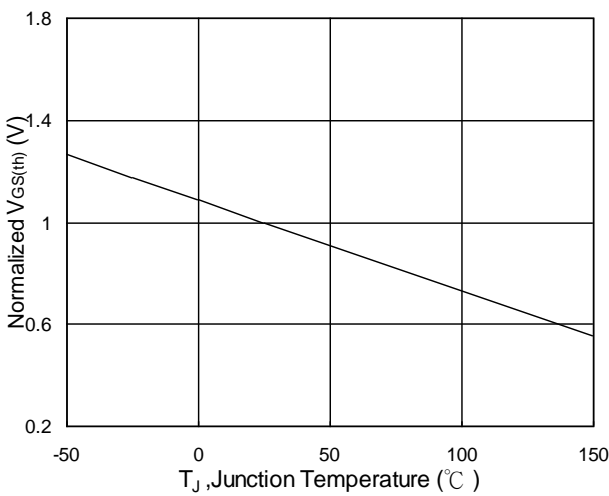


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

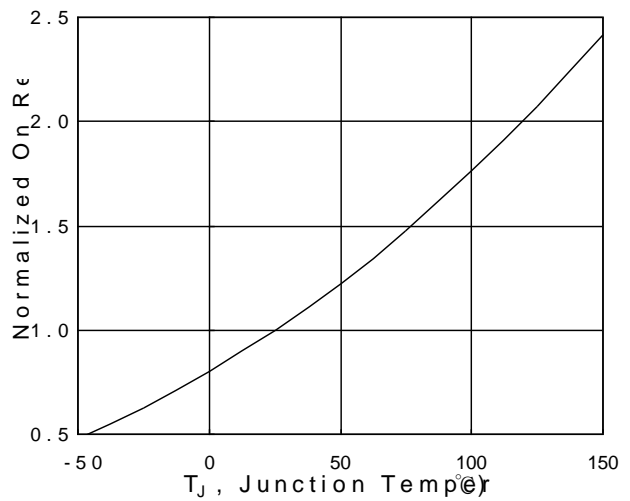


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

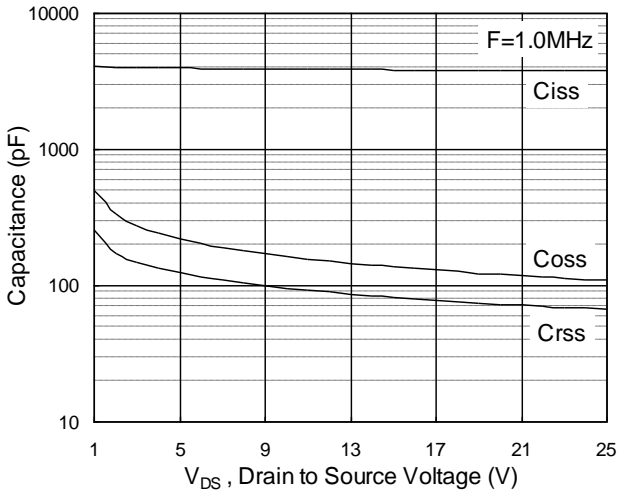


Fig.7 Capacitance

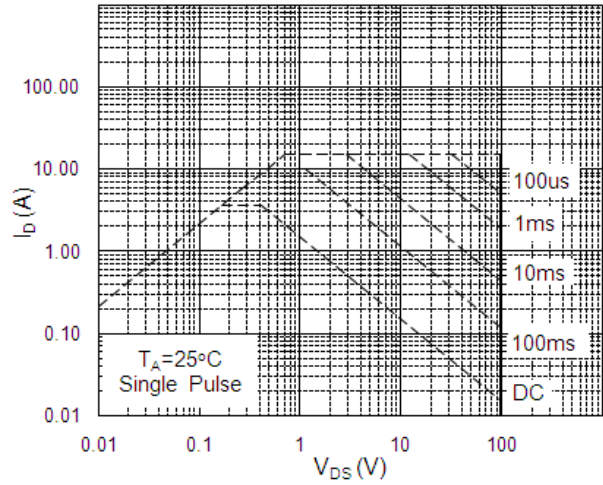


Fig.8 Safe Operating Area

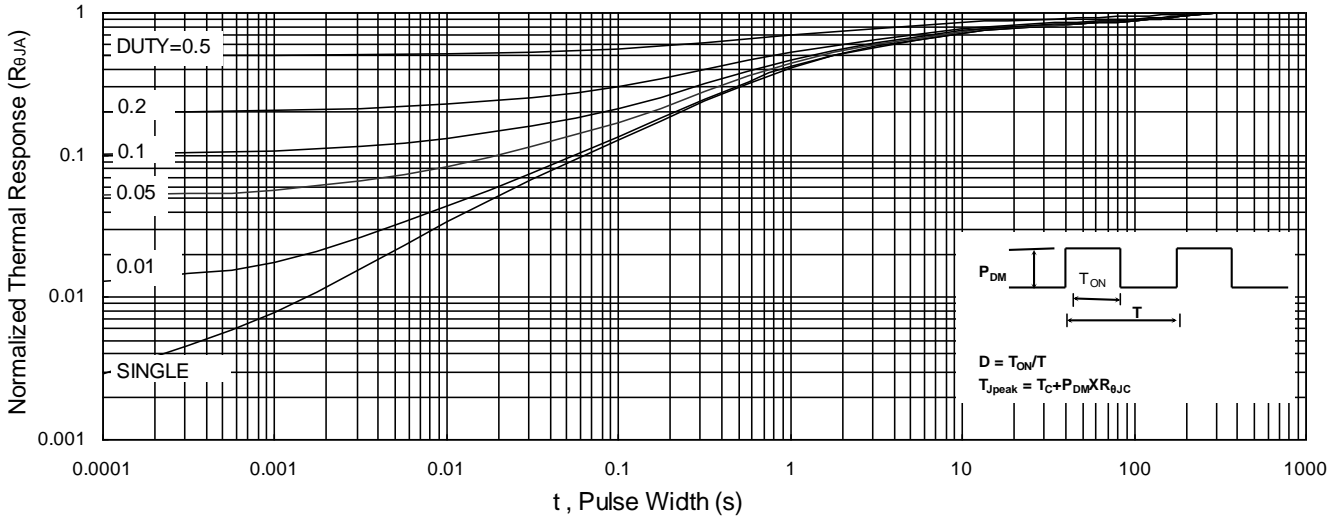


Fig.9 Normalized Maximum Transient Thermal Impedance

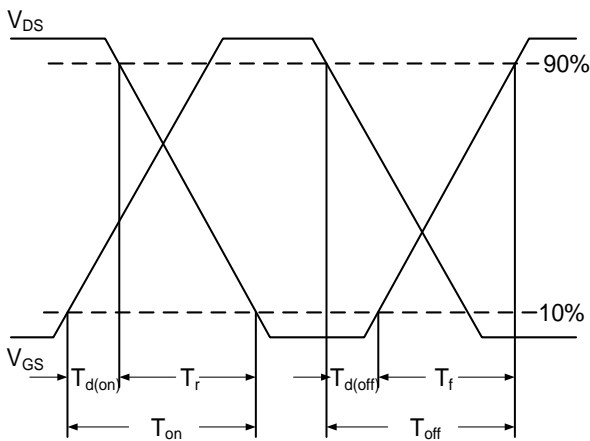


Fig.10 Switching Time Waveform

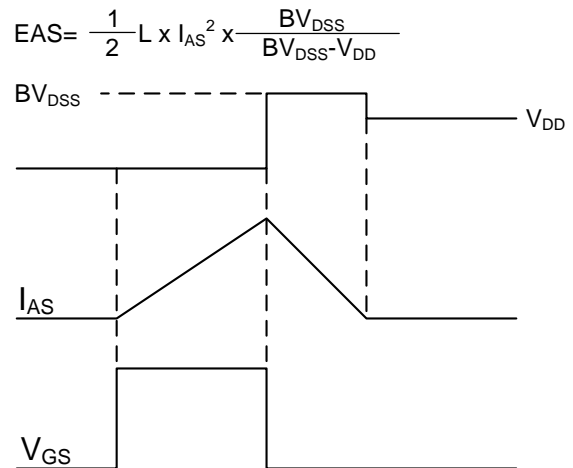


Fig.11 Unclamped Inductive Switching Waveform